Special Issue

Digital Twins in Industries and Beyond

Message from the Guest Editors

There have been significant developments in digital twin technologies in the last decade. This volume intends to cover the nonengineering applications of DT, such as those recently applied in defense, healthcare, arts, skills transfer, and learning, as well as other socio-economic utilizations of DT technology. Integrations of DT with other technologies, such as VR/AR, finite element analysis, cloud and edge platforms, microservice, etc., are most welcome as they complement DT technologies well. This Special Issue is soliciting conceptual, theoretical, and experimental contributions, in addition to discussing and treating challenges and solutions to a set of currently unresolved key challenges. Please note that all submissions should fit the primary scope of Future Internet. **keywords:**

- digital twins
- technologies integration
- learning digital twins
- defense
- healthcare
- learning and education
- industrial applications
- socioeconomic digital twin applications

Guest Editors

Prof. Dr. Soh Khim Ong

Department of Mechanical Engineering, National University of Singapore, 9 Engineering Drive 1, Singapore 117576, Singapore

Prof. Dr. Andrew Yeh Ching Nee

Department of Mechanical Engineering, National University of Singapore, 9 Engineering Drive 1, Singapore 117576, Singapore

Deadline for manuscript submissions

closed (20 February 2024)

Future Internet

About the Journal

Message from the Editor-in-Chief

Future Internet is a fast-growing journal devoted to rapid publications of the latest results in the general areas of computer networking/communications and information systems, with a focus on the Internet of Things, big data and augmented intelligence, smart systems (in terms of technologies, architectures, and applications), network virtualization, edge/fog computing, and cybersecurity. Both theoretical and experimental papers are welcome. Every year, *Future Internet* also features Special Issues dedicated to specific topics within the journal's scope.

Editor-in-Chief

Prof. Dr. Gianluigi Ferrari
Department of Engineering and Architecture, University of Parma,
Parco Area delle Scienze, 181/A, 43124 Parma, Italy

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